

Document Title

256Kx16 bit Dynamic RAM with EDO Page Mode

Revision History

Revision No	History	Draft Date	<u>Remark</u>
0A	Initial Draft	August 9,2001	01
0B	Revise for typo on page 20	December 18,20	
0C	Add Pb-free package	April 23,2004	

The attached datasheets are provided by ICSI. Integrated Circuit Solution Inc reserve the right to change the specifications and products. ICSI will answer to your questions about device. If you have any questions, please contact the ICSI offices.



256K x 16 (4-MBIT) DYNAMIC RAM WITH EDO PAGE MODE

FEATURES

- Extended Data-Out (EDO) Page Mode access cycle
- TTL compatible inputs and outputs; tristate I/O
- Refresh Interval: 512 cycles /8 ms
- Refresh Mode: RAS-Only, CAS-before-RAS (CBR), Hidden
- Single power supply: 5V ± 10% (IC41C16256) 3.3V ± 10% (IC41LV16256)
- Byte Write and Byte Read operation via two CAS
- Industrail Temperature Range -40°C to 85°C
- Pb-free package is available

DESCRIPTION

The *ICSI* IC41C16256 and IC41LV16256 is a 262,144 x 16bit high-performance CMOS Dynamic Random Access Memories. The IC41C16256 offer an accelerated cycle access called EDO Page Mode. EDO Page Mode allows 512 random accesses within a single row with access cycle time as short as 10 ns per 16-bit word. The Byte Write control, of upper and lower byte, makes the IC41C16256 ideal for use in 16-, 32-bit wide data bus systems.

These features make the IC41C16256and IC41LV16256 ideally suited for high-bandwidth graphics, digital signal processing, high-performance computing systems, and peripheral applications.

The IC41C16256 is packaged in a 40-pin 400mil SOJ and 400mil TSOP-2.

KEY TIMING PARAMETERS

Parameter	-25(5V)	-35	-50	-60	Unit
Max. RAS Access Time (tRAC)	25	35	50	60	ns
Max. CAS Access Time (tcac)	8	10	14	15	ns
Max. Column Address Access Time (tAA)	12	18	25	30	ns
Min. EDO Page Mode Cycle Time (tpc)	10	12	20	25	ns
Min. Read/Write Cycle Time (tRC)	45	60	90	110	ns

PIN CONFIGURATIONS 40-Pin TSOP-2

	1 • 2 3	40 GND 39 I I/O15 38 I I/O14
I/O2 ∐ I/O3 ∐ VCC ∐ I/O4 ∐	4 5 6 7	37 I/O13 36 I/O12 35 GND 34 I/O11
I/O5 ∐ I/O6 ∐ I/O7 ∏	8 9 10	33 /O10 32 /O9 31 /O8
NC NC RAS A0 A1 A2 A3 VCC	11 12 13 14 15 16 17 18 19 20	30 NC 29 LCAS 28 UCAS 27 OE 26 A8 25 A7 24 A6 23 A5 22 A4 21 GND

40-Pin SOJ

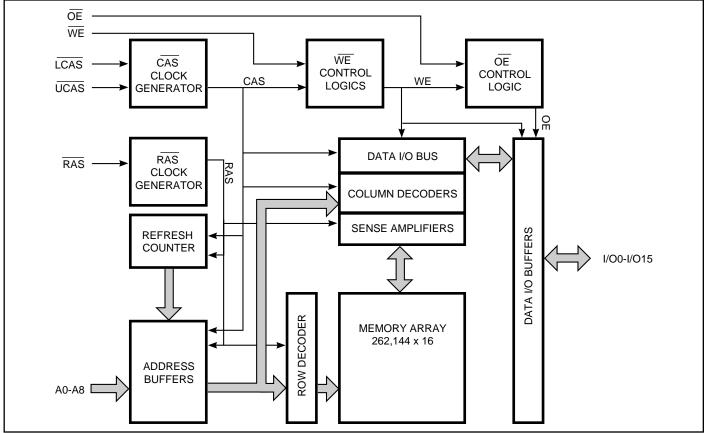
			$\overline{\mathbf{O}}$	I
	VCC [1	40	GND
	I/O0 [2	39	I/O15
	I/O1 [3	38	I/O14
	I/O2	4	37	I/O13
	I/O3 [5	36	I/O12
	VCC [6	35	GND
	I/O4 [7	34	I/O11
	I/O5 [8	33	I/O10
	I/O6	9	32	I/O9
	I/O7 [10	31	I/O8
	NC [11	30	NC
	NC [12	29	LCAS
-	WE [13	28	UCAS
5	RAS	14	27	ŌE
	NC [15	26	A8
	A0 [16	25	A7
	A1 [17	24	A6
	A2 [18	23	A5
	A3 [19	22	A4
	VCC [20	21	GND
		L		l

PIN DESCRIPTIONS

I/O0-15 E WE V OE C RAS F UCAS L	Address Inputs Data Inputs/Outputs Write Enable Dutput Enable Row Address Strobe
WE V OE C RAS F UCAS L	Vrite Enable Dutput Enable
OE C RAS F UCAS L	Dutput Enable
RAS F	•
	Row Address Strobe
LCAS L	Jpper Column Address Strobe
	ower Column Address Strobe
Vcc F	Power
GND G	Ground
NC N	No Connection



FUNCTIONAL BLOCK DIAGRAM





TRUTH TABLE

Function		RAS	LCAS	UCAS	WE	ŌĒ	Address tr/tc	I/O
Standby		Н	Н	Н	Х	Х	Х	High-Z
Read: Word		L	L	L	Н	L	ROW/COL	Dout
Read: Lower Byte		L	L	Н	Н	L	ROW/COL	Lower Byte, Dout Upper Byte, High-Z
Read: Upper Byte		L	Н	L	Н	L	ROW/COL	Lower Byte, High-Z Upper Byte, Dout
Write: Word (Early Write)		L	L	L	L	Х	ROW/COL	Din
Write: Lower Byte (Early \	Write)	L	L	Н	L	Х	ROW/COL	Lower Byte, Dıℕ Upper Byte, High-Z
Write: Upper Byte (Early V	Write)	L	Η	L	L	Х	ROW/COL	Lower Byte, High-Z Upper Byte, Dıℕ
Read-Write ^(1,2)		L	L	L	H→L	L→H	ROW/COL	Dout, Din
EDO Page-Mode Read ⁽²⁾	1st Cycle:	L	H→L	H→L	Н	L	ROW/COL	Dout
	2nd Cycle:	L	H→L	H→L	Н	L	NA/COL	Dout
	Any Cycle:	L	L→H	L→H	Н	L	NA/NA	Dout
EDO Page-Mode Write ⁽¹⁾	1st Cycle:	L	H→L	H→L	L	Х	ROW/COL	Din
	2nd Cycle:	L	H→L	H→L	L	Х	NA/COL	Din
EDO Page-Mode	1st Cycle:	L	H→L	H→L	H→L	L→H	ROW/COL	Dout, Din
Read-Write ^(1,2)	2nd Cycle:	L	$H \rightarrow L$	H→L	H→L	$L \rightarrow H$	NA/COL	Dout, Din
Hidden Refresh ⁽²⁾	Read L	_→H→L	L	L	Н	L	ROW/COL	Dout
	Write L	_→H→L	L	L	L	Х	ROW/COL	Dout
RAS-Only Refresh		L	Н	Н	Х	Х	ROW/NA	High-Z
CBR Refresh ⁽³⁾		H→L	L	L	Х	Х	Х	High-Z

Notes:

These WRITE cycles may also be BYTE WRITE cycles (either LCAS or UCAS active).
 These READ cycles may also be BYTE READ cycles (either LCAS or UCAS active).
 At least one of the two CAS signals must be active (LCAS or UCAS).



Functional Description

The IC41C16256 and IC41LV16256 is a CMOS DRAM optimized for high-speed bandwidth, low power applications. During READ or WRITE cycles, each bit is uniquely addressed through the 18 address bits. These are entered 9 bits (A0-A8) at a time. The row address is latched by the Row Address Strobe (RAS). The column address is latched by the Column Address Strobe (CAS).

The IC41C16256 and IC41LV16256 has two CAS controls, ICAS and UCAS. The ICAS and UCAS inputs internally generates a CAS signal functioning in an identical manner to the single CAS input on the other 256K x 16 DRAMs. The key difference is that each CAS controls its corresponding I/O tristate logic (in conjunction with OE and WE and RAS). ICAS controls I/O0 through I/O7 and UCAS controls I/O8 through I/O15.

The IC41C16256 and IC41LV16256 CAS function is determined by the first CAS (LCAS or UCAS) transitioning LOW and the last transitioning back HIGH. The two CAS controls give the IC41C16256 both BYTE READ and BYTE WRITE cycle capabilities.

Memory Cycle

A memory cycle is initiated by bring \overrightarrow{RAS} LOW and it is terminated by returning both \overrightarrow{RAS} and \overrightarrow{CAS} HIGH. To ensures proper device operation and data integrity any memory cycle, once initiated, must not be ended or aborted before the minimum tras time has expired. A new cycle must not be initiated until the minimum precharge time trap, tcp has elapsed.

Read Cycle

A read cycle is initiated by the falling edge of \overline{CAS} or \overline{OE} , whichever occurs last, while holding \overline{WE} HIGH. The column address must be held for a minimum time specified by tar. Data Out becomes valid only when trac, taa, tcac and toe are all satisfied. As a result, the access time is dependent on the timing relationships between these parameters.

Write Cycle

A write cycle is initiated by the falling edge of CAS and WE, whichever occurs last. The input data must be valid at or before the falling edge of CAS or WE, whichever occurs first.

Refresh Cycle

To retain data, 512 refresh cycles are required in each 8 ms period. There are two ways to refresh the memory.

- 1. By clocking each of the 512 row addresses (A0 through A8) with RAS at least once every 8 ms. Any read, write, read-modify-write or RAS-only cycle refreshes the addressed row.
- 2. Using a CAS-before-RAS refresh cycle. CAS-before-RAS refresh is activated by the falling edge of RAS, while holding CAS LOW. In CAS-before-RAS refresh cycle, an internal 9-bit counter provides the row addresses and the external address inputs are ignored.

CAS-before-RAS is a refresh-only mode and no data access or device selection is allowed. Thus, the output remains in the High-Z state during the cycle.

Extended Data Out Page Mode

EDO page mode operation permits all 512 columns within a selected row to be randomly accessed at a high data rate.

In EDO page mode read cycle, the data-out is held to the next CAS cycle's falling edge, instead of the rising edge. For this reason, the valid data output time in EDO page mode is extended compared with the fast page mode. In the fast page mode, the valid data output time becomes shorter as the CAS cycle time becomes shorter. Therefore, in EDO page mode, the timing margin in read cycle is larger than that of the fast page mode even if the CAS cycle time becomes shorter.

In EDO page mode, due to the extended data function, the \overline{CAS} cycle time can be shorter than in the fast page mode if the timing margin is the same.

The EDO page mode allows both read and write operations during one \overline{RAS} cycle, but the performance is equivalent to that of the fast page mode in that case.

Power-On

After application of the Vcc supply, an initial pause of 200 μ s is required followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS signal).

During power-on, it is recommended that \overline{RAS} track with Vcc or be held at a valid VIH to avoid current surges.



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameters		Rating	Unit
VT	Voltage on Any Pin Relative to GND	5V	-1.0 to +7.0	V
		3.3V	–0.5 to +4.6	
Vcc	Supply Voltage	5V	-1.0 to +7.0	V
		3.3V	–0.5 to +4.6	
Ιουτ	Output Current		50	mA
PD	Power Dissipation		1	W
TA	Commercial Operation Temperature		0 to +70	°C
	Industrial Operationg Temperature		-40 to +85	°C
Tstg	Storage Temperature		–55 to +125	°C

Note:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED OPERATING CONDITIONS (Voltages are referenced to GND.)

Symbol	Parameter		Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	5V	4.5	5.0	5.5	V
		3.3V	3.0	3.3	3.6	
Vін	Input High Voltage	5V	2.4	_	Vcc + 1.0	V
		3.3V	2.0	_	Vcc + 0.3	
VIL	Input Low Voltage	5V	-1.0	_	0.8	V
		3.3V	-0.3	—	0.8	
Та	Commercial Ambient Temperature		0	_	70	°C
	Industrial Ambient Temperature		-40	—	85	°C

CAPACITANCE^(1,2)

Symbol	Parameter	Max.	Unit
CIN1	Input Capacitance: A0-A8	5	pF
CIN2	Input Capacitance: RAS, UCAS, LCAS, WE, OE	7	pF
Сю	Data Input/Output Capacitance: I/O0-I/O15	7	pF

Notes:

1. Tested initially and after any design or process changes that may affect these parameters.

2. Test conditions: $T_A = 25^{\circ}C$, f = 1 MHz.



ELECTRICAL CHARACTERISTICS⁽¹⁾

(Recommended Operating Conditions unless otherwise noted.)

Symbol	Parameter	Test Condition	Speed	Min.	Max.	Unit
lil	Input Leakage Current	Any input 0V < V _{IN} < Vcc Other inputs not under test = 0V		-10	10	μA
lio	Output Leakage Current	Output is disabled (Hi-Z) 0V < Vout < Vcc		-10	10	μA
Vон	Output High Voltage Level	Іон = –2.5 mA		2.4	—	V
Vol	Output Low Voltage Level	loL =+2.1mA			0.4	V
lcc1	Standby Current: TTL	RAS, LCAS, UCAS > V _I H Commerical Industrial Commerical Industrial	5V		2 3 1 2	mA
lcc2	Standby Current: CMOS	\overline{RAS} , \overline{LCAS} , $\overline{UCAS} > V_{CC} - 0.2V$	5V 3.3V	_	1 0.5	mA
Icc3	Operating Current: Random Read/Write ^(2,3,4) Average Power Supply Current	RAS, LCAS, UCAS, Address Cycling, trc = trc (min.)	-25 -35 -50 -60	 	260 230 180 170	mA
Icc4	Operating Current: EDO Page Mode ^(2,3,4) Average Power Supply Current	$\overline{RAS} = V_{IL}, \overline{LCAS}, \overline{UCAS},$ Cycling tPc = tPc (min.)	-25 -35 -50 -60		250 220 170 160	mA
Icc5	Refresh Current: RAS-Only ^(2,3) Average Power Supply Current	RAS Cycling, LCAS, UCAS > VIH trc = trc (min.)	-25 -35 -50 -60		260 230 180 170	mA
Icc6	Refresh Current: CBR ^(2,3,5) Average Power Supply Current	RAS, LCAS, UCAS Cycling trc = trc (min.)	-25 -35 -50 -60		260 230 180 170	mA

Notes:

1. An initial pause of 200 µs is required after power-up followed by eight RAS refresh cycles (RAS-Only or CBR) before proper device operation is assured. The eight RAS cycles wake-up should be repeated any time the tREF refresh requirement is exceeded.

2. Dependent on cycle rates.

3. Specified values are obtained with minimum cycle time and the output open.

4. Column-address is changed once each EDO page cycle.

5. Enables on-chip refresh and address counters.



AC CHARACTERISTICS^(1,2,3,4,5,6)

(Recommended Operating Conditions unless otherwise noted.)

			25	-;	35	-	50	-(60	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t RC	Random READ or WRITE Cycle Time	45	_	60		90	_	110	_	ns
t RAC	Access Time from RAS ^(6, 7)	_	25		35		50		60	ns
tcac	Access Time from CAS ^(6, 8, 15)	—	8	—	10		14	—	15	ns
taa	Access Time from Column-Address ⁽⁶⁾		12		18		25	_	30	ns
tras	RAS Pulse Width	25	10K	35	10K	50	10K	60	10K	ns
t RP	RAS Precharge Time	15	_	20	_	30	_	40		ns
tcas	CAS Pulse Width ⁽²⁶⁾	4	10K	6	10K	8	10K	10	10K	ns
tcp	CAS Precharge Time ^(9, 25)	4	_	5		8		10		ns
tcsн	CAS Hold Time ⁽²¹⁾	25	_	35		50		60		ns
trcd	RAS to CAS Delay Time ^(10, 20)	10	17	11	28	19	36	20	45	ns
tasr	Row-Address Setup Time	0	_	0		0	_	0		ns
traн	Row-Address Hold Time	6	_	6		8	_	10	_	ns
tasc	Column-Address Setup Time ⁽²⁰⁾	0	_	0	_	0		0		ns
tсан	Column-Address Hold Time ⁽²⁰⁾	5	_	6		8		10		ns
tar	Column-Address Hold Time (referenced to RAS)	19	—	30	—	40	—	40	—	ns
trad	RAS to Column-Address Delay Time ⁽¹¹⁾	8	20	10	20	14	25	15	30	ns
t RAL	Column-Address to RAS Lead Time	12	_	18		25	_	30		ns
t RPC	RAS to CAS Precharge Time	0	_	0		0	_	0	_	ns
t RSH	RAS Hold Time ⁽²⁷⁾	7	_	8		14	_	15		ns
t clz	CAS to Output in Low-Z ^(15, 29)	3	_	3		3		3		ns
t CRP	CAS to RAS Precharge Time ⁽²¹⁾	5	_	5		5	_	5	_	ns
tod	Output Disable Time ^(19, 28, 29)	2	12	3	12	3	12	3	12	ns
t OE	Output Enable Time ^(15, 16)	0	8	0	10	0	15	_	15	ns
tоенс	OE HIGH Hold Time from CAS HIGH	10	_	10		10		10	_	ns
t OEP	OE HIGH Pulse Width	10	_	10	_	10		10	_	ns
toes	OE LOW to CAS HIGH Setup Time	5	_	5	_	5		5	_	ns
trcs	Read Command Setup Time ^(17, 20)	0	_	0		0	_	0		ns
t RRH	Read Command Hold Time (referenced to RAS) ⁽¹²⁾	0	_	0		0	_	0		ns
trcн	Read Command Hold Time (referenced to CAS) ^(12, 17, 21)	0	_	0	_	0	_	0		ns
twcн	Write Command Hold Time ^(17, 27)	5	_	5		8		10		ns
twcr	Write Command Hold Time (referenced to RAS) ⁽¹⁷⁾	19		30	_	40		50		ns
twp	Write Command Pulse Width ⁽¹⁷⁾	5	_	5		8	_	10	_	ns
twpz	WE Pulse Widths to Disable Outputs	10	_	10		10	_	10	_	ns
trwL	Write Command to RAS Lead Time ⁽¹⁷⁾	7	_	8		14	_	15		ns
tcwL	Write Command to CAS Lead Time ^(17, 21)	5	_	8		14		15		ns
twcs	Write Command Setup Time ^(14, 17, 20)	0	_	0		0		0		ns
tohr .	Data-in Hold Time (referenced to RAS)	19		30		40		40		ns



AC CHARACTERISTICS (Continued)(1,2,3,4,5,6)

(Recommended Operating Conditions unless otherwise noted.)

			-25		35	-	50	-(60	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
tасн	Column-Address Setup Time to CAS Precharge during WRITE Cycle	15	—	15	—	15	_	15	—	ns
tоен	OE Hold Time from WE during READ-MODIFY-WRITE cycle ⁽¹⁸⁾	5	_	8	_	10	_	15		ns
tos	Data-In Setup Time ^(15, 22)	0		0		0		0	_	ns
tdн	Data-In Hold Time ^(15, 22)	5		6		8		10	_	ns
trwc	READ-MODIFY-WRITE Cycle Time	65		80		125		140	_	ns
trwd	RAS to WE Delay Time during READ-MODIFY-WRITE Cycle ⁽¹⁴⁾	35	_	45	_	70	_	80		ns
tcwp	CAS to WE Delay Time ^(14, 20)	17		25	_	34	_	36	_	ns
tawd	Column-Address to WE Delay Time ⁽¹⁴⁾	21		30		42		49	_	ns
t PC	EDO Page Mode READ or WRITE Cycle Time ⁽²⁴⁾	10	_	12	_	20	_	25		ns
t RASP	RAS Pulse Width in EDO Page Mode	25	100K	35	100K	50	100K	50	100K	ns
t CPA	Access Time from CAS Precharge ⁽¹⁵⁾		14	_	21	_	27	_	34	ns
t PRWC	EDO Page Mode READ-WRITE Cycle Time ⁽²⁴⁾	32	—	40	_	47	—	56	—	ns
tсон	Data Output Hold after CAS LOW	5		5		5		5	_	ns
toff	Output Buffer Turn-Off Delay from CAS or RAS ^(13,15,19, 29)	3	15	3	15	3	15	3	15	ns
twнz	Output Disable Delay from WE	3	15	3	15	3	15	3	15	ns
tсьсн	Last CAS going LOW to First CAS returning HIGH ⁽²³⁾	10	_	10	_	10	_	10	_	ns
tcsr	CAS Setup Time (CBR REFRESH)(30, 20)	5	_	8		10	_	10		ns
t CHR	CAS Hold Time (CBR REFRESH) ^(30, 21)	7	_	8	_	10		10	_	ns
tord	OE Setup Time prior to RAS during HIDDEN REFRESH Cycle	0	_	0	_	0	—	0	—	ns
t REF	Refresh Period (512 Cycles)		8		8	8		8	_	ms
t⊤	Transition Time (Rise or Fall) ^(2, 3)	1	50	1	50	1	50	1	50	ns

AC TEST CONDITIONS

Output load:

Two TTL Loads and 50 pF (Vcc = $5.0V \pm 10\%$) One TTL Load and 50 pF (Vcc = $3.3V \pm 10\%$)

Input timing reference levels: $V_{IH} = 2.4V$, $V_{IL} = 0.8V$ (Vcc = 5.0V ±10%); $V_{IH} = 2.0V$, $V_{IL} = 0.8V$ (Vcc = 3.3V ±10%)

Output timing reference levels: $V_{OH} = 2.0V$, $V_{OL} = 0.8V$ (Vcc = 5V ±10%, 3.3V ±10%)

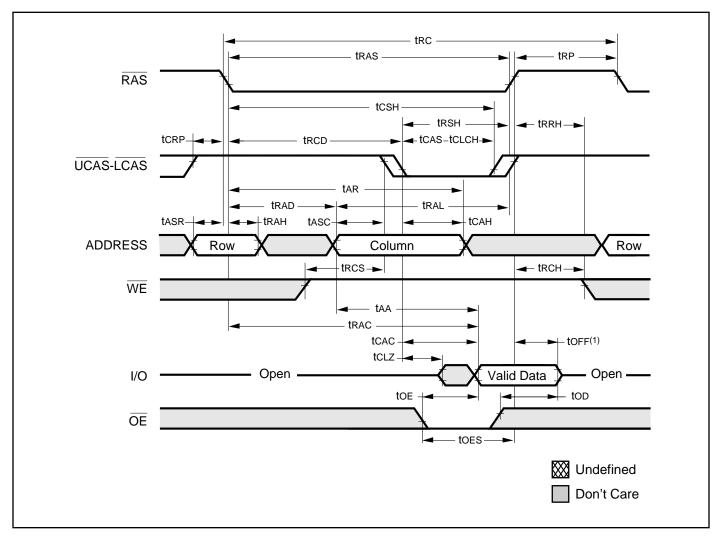


Notes:

- 1. An initial pause of 200 µs is required after power-up followed by eight RAS refresh cycle (RAS-Only or CBR) before proper device operation is assured. The eight RAS cycles wake-up should be repeated any time the tREF refresh requirement is exceeded.
- V_IH (MIN) and V_IL (MAX) are reference levels for measuring timing of input signals. Transition times, are measured between V_IH and V_IL (or between V_IL and V_IH) and assume to be 1 ns for all inputs.
- 3. In addition to meeting the transition rate specification, all input signals must transit between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}) in a monotonic manner.
- 4. If \overline{CAS} and \overline{RAS} = VIH, data output is High-Z.
- 5. If $\overline{CAS} = V_{IL}$, data output may contain data from the last valid READ cycle.
- 6. Measured with a load equivalent to one TTL gate and 50 pF.
- 7. Assumes that tRCD ≤ tRCD (MAX). If tRCD is greater than the maximum recommended value shown in this table, tRAC will increase by the amount that tRCD exceeds the value shown.
- 8. Assumes that $t_{RCD} \ge t_{RCD}$ (MAX).
- 9. If CAS is LOW at the falling edge of RAS, data out will be maintained from the previous cycle. To initiate a new cycle and clear the data output buffer, CAS and RAS must be pulsed for tcp.
- 10. Operation with the trcb (MAX) limit ensures that trac (MAX) can be met. trcb (MAX) is specified as a reference point only; if trcb is greater than the specified trcb (MAX) limit, access time is controlled exclusively by tcac.
- 11. Operation within the trad (MAX) limit ensures that trcd (MAX) can be met. trad (MAX) is specified as a reference point only; if trad is greater than the specified trad (MAX) limit, access time is controlled exclusively by taa.
- 12. Either tRCH or tRRH must be satisfied for a READ cycle.
- 13. toFF (MAX) defines the time at which the output achieves the open circuit condition; it is not a reference to VOH or VOL.
- 14. twcs, trwb, tawb and tcwb are restrictive operating parameters in LATE WRITE and READ-MODIFY-WRITE cycle only. If twcs ≥ twcs (MIN), the cycle is an EARLY WRITE cycle and the data output will remain open circuit throughout the entire cycle. If trwb ≥ trwb (MIN), tawb ≥ tawb (MIN) and tcwb ≥ tcwb (MIN), the cycle is a READ-WRITE cycle and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of I/O (at access time and until CAS and RAS or OE go back to VIH) is indeterminate. OE held HIGH and WE taken LOW after CAS goes LOW result in a LATE WRITE (OE-controlled) cycle.
- 15. Output parameter (I/O) is referenced to corresponding CAS input, I/O0-I/O7 by LCAS and I/O8-I/O15 by UCAS.
- 16. During a READ cycle, if OE is LOW then taken HIGH before CAS goes HIGH, I/O goes open. If OE is tied permanently LOW, a LATE WRITE or READ-MODIFY-WRITE is not possible.
- 17. Write command is defined as $\overline{\text{WE}}$ going low.
- 18. LATE WRITE and READ-MODIFY-WRITE cycles must have both top and toEH met (OE HIGH during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycle. The I/Os will provide the previously written data if CAS remains LOW and OE is taken back to LOW after toEH is met.
- 19. The I/Os are in open during READ cycles once top or topp occur.
- 20. The first $\chi \overline{CAS}$ edge to transition LOW.
- 21. The last $\chi \overline{CAS}$ edge to transition HIGH.
- 22. These parameters are referenced to CAS leading edge in EARLY WRITE cycles and WE leading edge in LATE WRITE or READ-MODIFY-WRITE cycles.
- 23. Last falling $\chi \overline{CAS}$ edge to first rising $\chi \overline{CAS}$ edge.
- 24. Last rising $\chi \overline{CAS}$ edge to next cycle's last rising $\chi \overline{CAS}$ edge.
- 25. Last rising $\chi \overline{CAS}$ edge to first falling $\chi \overline{CAS}$ edge.
- 26. Each $\chi \overline{CAS}$ must meet minimum pulse width.
- 27. Last $\chi \overline{CAS}$ to go LOW.
- 28. I/Os controlled, regardless $\overline{\text{UCAS}}$ and $\overline{\text{LCAS}}$.
- 29. The 3 ns minimum is a parameter guaranteed by design.
- 30. Enables on-chip refresh and address counters.



READ CYCLE

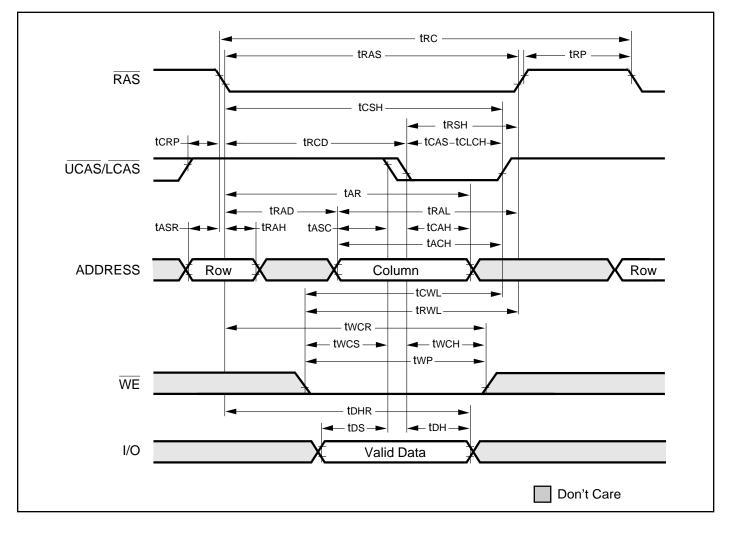


Note:

1. toff is referenced from rising edge of RAS or CAS, whichever occurs last.

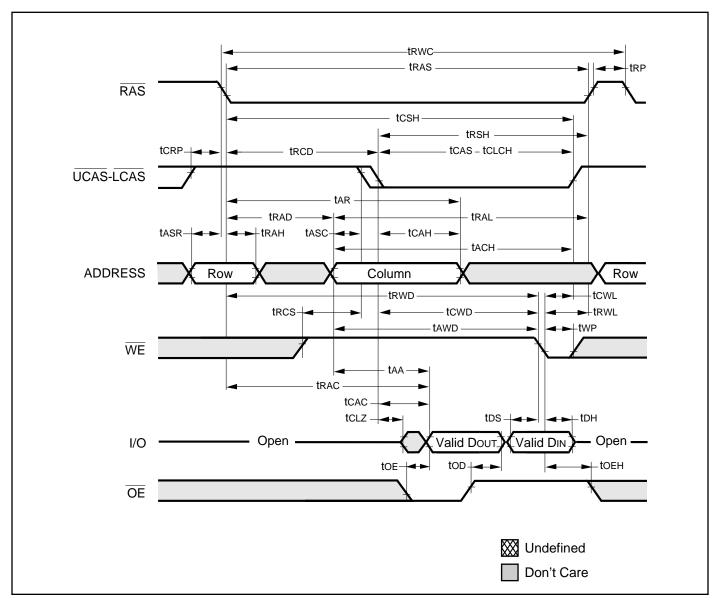


EARLY WRITE CYCLE (OE = DON'T CARE)



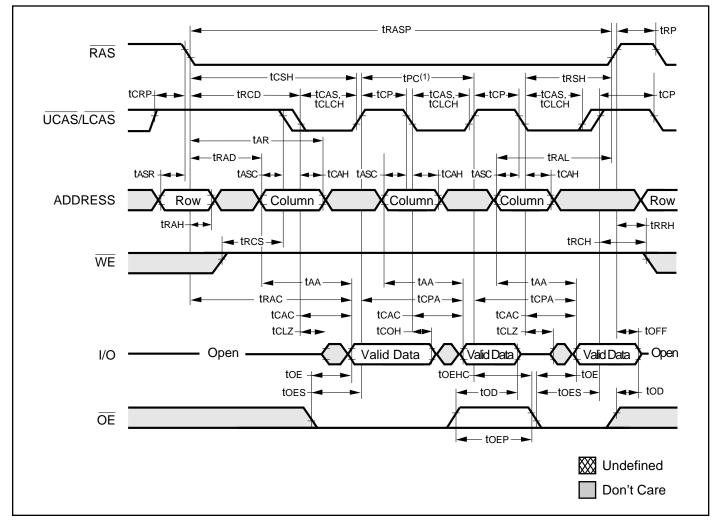


READ WRITE CYCLE (LATE WRITE and READ-MODIFY-WRITE Cycles)





EDO-PAGE-MODE READ CYCLE

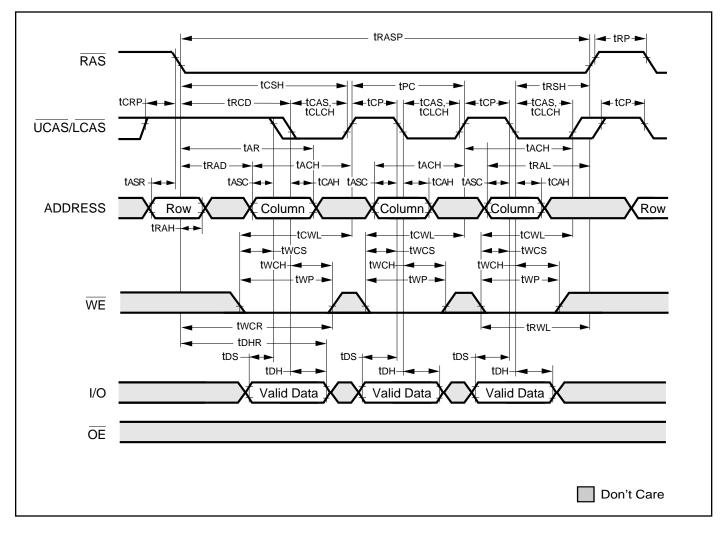


Note:

1. tPc can be measured from falling edge of CAS to falling edge of CAS, or from rising edge of CAS to rising edge of CAS. Both measurements must meet the tPc specifications.

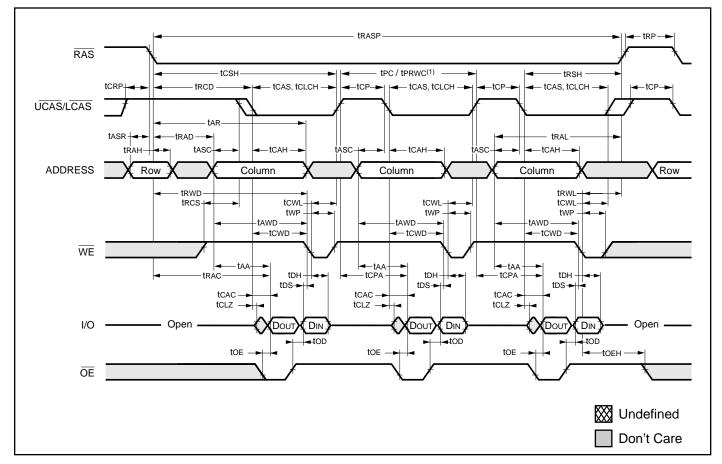


EDO-PAGE-MODE EARLY-WRITE CYCLE





EDO-PAGE-MODE READ-WRITE CYCLE (LATE WRITE and READ-MODIFY WRITE Cycles)

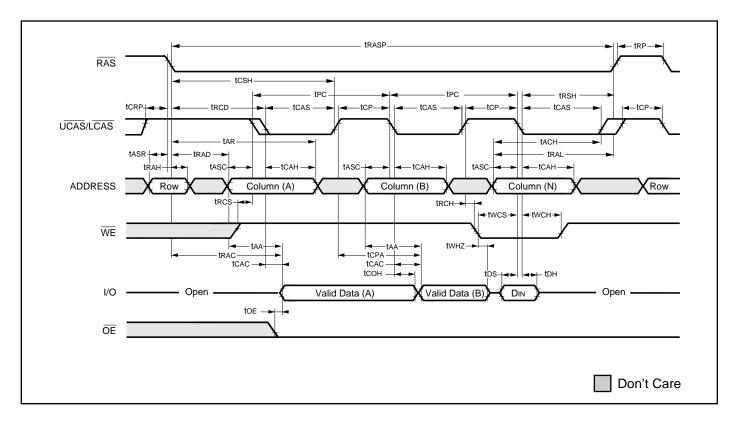


Note:

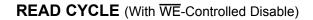
1. tPc is for LATE write cycles only. tPc can be measured from falling edge of CAS to falling edge of CAS, or from rising edge of CAS. Both measurements must meet the tPc specifications.

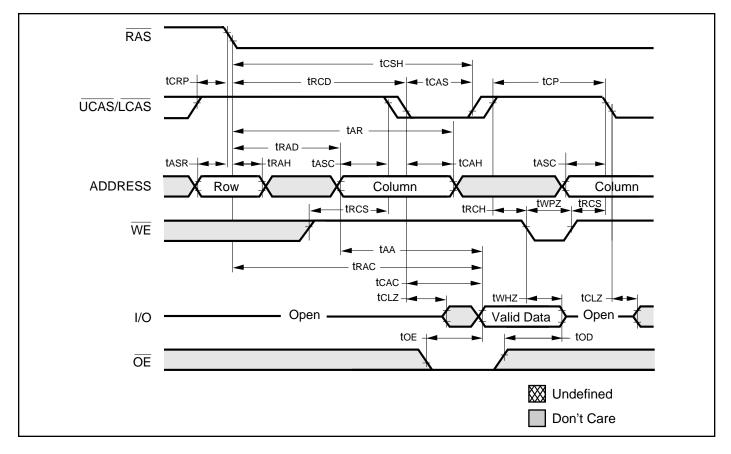


EDO-PAGE-MODE READ-EARLY-WRITE CYCLE (Psuedo READ-MODIFY WRITE)

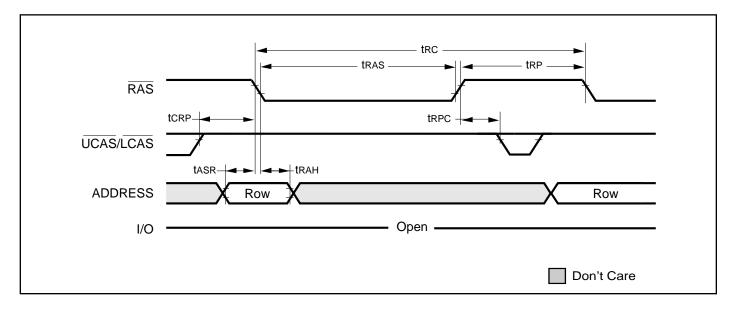


AC WAVEFORMS



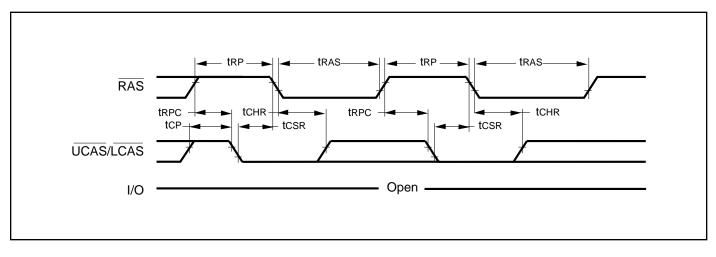


RAS-ONLY REFRESH CYCLE (OE, WE = DON'T CARE)

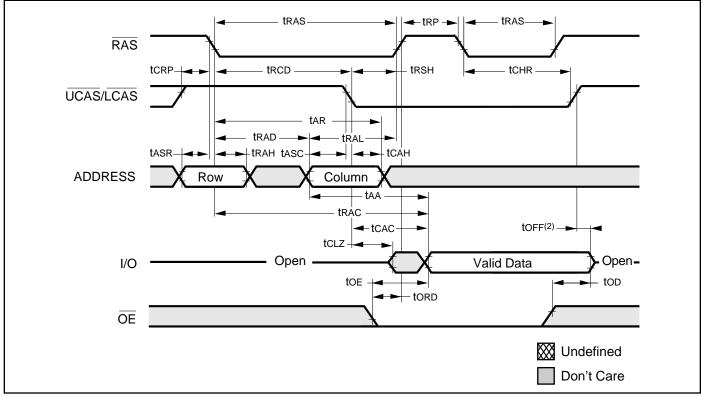




CBR REFRESH CYCLE (Addresses; \overline{WE} , \overline{OE} = DON'T CARE)



HIDDEN REFRESH CYCLE⁽¹⁾ (WE = HIGH; OE = LOW)



Notes:

1. A Hidden Refresh may also be performed after a Write Cycle. In this case, \overline{WE} = LOW and \overline{OE} = HIGH. 2. toFF is referenced from rising edge of RAS or CAS, whichever occurs last.



ORDERING INFORMATION (Pb-free)

IC41C16256

Commercial Range: 0°C to 70°C

Speed (ns)	Order Part No.	Package
25	IC41C16256-25K(G) IC41C16256-25T(G)	400mil SOJ(Pb-free) 400mil TSOP-2(Pb-free)
35	IC41C16256-35K(G) IC41C16256-35T(G)	400mil SOJ(Pb-free) 400mil TSOP-2(Pb-free)
50	IC41C16256-50K(G) IC41C16256-50T(G)	400mil SOJ(Pb-free) 400mil TSOP-2(Pb-free)
60	IC41C16256-60K(G) IC41C16256-60T(G)	400mil SOJ(Pb-free) 400mil TSOP-2(Pb-free)

ORDERING INFORMATION (Pb-free) IC41C16256

Industrial Range: -40°C to 85°C

Speed (ns)	Order Part No.	Package
25	IC41C16256-25KI(G) IC41C16256-25TI(G)	400mil SOJ(Pb-free) 400mil TSOP-2(Pb-free)
35	IC41C16256-35KI(G) IC41C16256-35TI(G)	400mil SOJ(Pb-free) 400mil TSOP-2(Pb-free)
50	IC41C16256-50KI(G) IC41C16256-50TI(G)	400mil SOJ(Pb-free) 400mil TSOP-2(Pb-free)
60	IC41C16256-60KI(G) IC41C16256-60TI(G)	400mil SOJ(Pb-free) 400mil TSOP-2(Pb-free)



ORDERING INFORMATION (Pb-free) IC41LV16256

Commercial Range: 0°C to 70°C

Speed (ns)	Order Part No.	Package
35	IC41LV16256-35K(G)	400mil SOJ(Pb-free)
	IC41LV16256-35T(G)	400mil TSOP-2(Pb-free)
50	IC41LV16256-50K(G)	400mil SOJ(Pb-free)
	IC41LV16256-50T(G)	400mil TSOP-2(Pb-free)
60	IC41LV16256-60K(G)	400mil SOJ(Pb-free)
	IC41LV16256-60T(G)	400mil TSOP-2(Pb-free)

ORDERING INFORMATION (Pb-free)

IC41LV16256

Industrial Range: -40°C to 85°C

Speed (ns)	Order Part No.	Package
35	IC41LV16256-35KI(G)	400mil SOJ(Pb-free)
	IC41LV16256-35TI(G)	400mil TSOP-2(Pb-free)
50	IC41LV16256-50KI(G)	400mil SOJ(Pb-free)
	IC41LV16256-50TI(G)	400mil TSOP-2(Pb-free)
60	IC41LV16256-60KI(G)	400mil SOJ(Pb-free)
	IC41LV16256-60TI(G)	400mil TSOP-2(Pb-free)



Integrated Circuit Solution Inc.

HEADQUARTER: NO.2, TECHNOLOGY RD. V, SCIENCE-BASED INDUSTRIAL PARK, HSIN-CHU, TAIWAN, R.O.C. TEL: 886-3-5780333 Fax: 886-3-5783000

> BRANCH OFFICE: 7F, NO. 106, SEC. 1, HSIN-TAI 5[™] ROAD, HSICHIH TAIPEI COUNTY, TAIWAN, R.O.C. TEL: 886-2-26962140 FAX: 886-2-26962252 http://www.icsi.com.tw